



Material Content Data Sheet



Halogen-Free

Sales Product Name	ICE2HS01G	Issued	24. June 2021
MA#	MA005429864		
Package	PG-DSO-20-45	Weight*	587.30 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.580	0.44	0.44	4392	4392
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		81	
	non noble metal	zinc	7440-66-6	0.190	0.03		323	
	non noble metal	iron	7439-89-6	3.797	0.65		6466	
	non noble metal	copper	7440-50-8	154.185	26.25	26.94	262534	269404
wire	noble metal	gold	7440-57-5	0.576	0.10	0.10	980	980
encapsulation	organic material	carbon black	1333-86-4	0.838	0.14		1427	
	plastics	epoxy resin	-	38.563	6.57		65661	
	inorganic material	silicondioxide	60676-86-0	379.758	64.66	71.37	646621	713709
leadfinish	non noble metal	tin	7440-31-5	4.487	0.76	0.76	7640	7640
plating	noble metal	silver	7440-22-4	0.800	0.14	0.14	1362	1362
glue	plastics	epoxy resin	-	0.369	0.06		628	
	noble metal	silver	7440-22-4	1.107	0.19	0.25	1885	2513
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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